

Wentao Qin

List of Publications by Year in descending order

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Version: 2024-02-01

23
papers

523
citations

1478505

6
h-index

888059

17
g-index

23
all docs

23
docs citations

23
times ranked

683
citing authors

#	ARTICLE	IF	CITATIONS
1	Promotion of water-mediated carbon removal by nanostructured barium oxide/nickel interfaces in solid oxide fuel cells. <i>Nature Communications</i> , 2011, 2, 357.	12.8	280
2	Direct octane fuel cells: A promising power for transportation. <i>Nano Energy</i> , 2012, 1, 448-455.	16.0	118
3	Impact of Ti/Al atomic ratio on the formation mechanism of non-recessed Au-free Ohmic contacts on AlGaIn/GaN heterostructures. <i>Journal of Applied Physics</i> , 2016, 120, .	2.5	31
4	Lattice parameters from direct-space images at two tilts. <i>Ultramicroscopy</i> , 2003, 94, 245-262.	1.9	20
5	Making sense of nanocrystal lattice fringes. <i>Journal of Applied Physics</i> , 2005, 98, 114308.	2.5	20
6	FIB failure analysis of memory arrays. <i>Microelectronic Engineering</i> , 2004, 75, 3-11.	2.4	16
7	Image-Based Nanocrystallography in Future Aberration-Corrected Transmission Electron Microscopes. <i>Materials Research Society Symposia Proceedings</i> , 2004, 818, 78.	0.1	6
8	Spontaneous oxide reduction in metal stacks. <i>Thin Solid Films</i> , 2005, 473, 236-240.	1.8	6
9	Towards 3D image-based nanocrystallography by means of transmission electron goniometry. <i>Materials Research Society Symposia Proceedings</i> , 2004, 839, 89.	0.1	4
10	Image-based nanocrystallography by means of transmission electron goniometry. <i>Nonlinear Analysis: Theory, Methods & Applications</i> , 2005, 63, e1323-e1331.	1.1	4
11	Lattice Fringe Visibility after Tilt. <i>Microscopy and Microanalysis</i> , 2000, 6, 1040-1041.	0.4	3
12	Probability of Seeing (001) Cross-Fringes in a Random Cubic Nanocrystal Image. <i>Microscopy and Microanalysis</i> , 2000, 6, 1038-1039.	0.4	3
13	Fringe-Covariance "Fingerprinting" of Nanoparticle Lattice Images. <i>Microscopy and Microanalysis</i> , 2004, 10, 1262-1263.	0.4	3
14	Oxide Impurities in Silicon Oxide Intermetal Dielectrics and Their Potential to Elevate Via-Resistances. <i>Microscopy and Microanalysis</i> , 2014, 20, 1271-1275.	0.4	3
15	High-Resolution Transmission Electron Microscope Analysis of Tungsten Carbide Thin Films. <i>Materials Research Society Symposia Proceedings</i> , 1998, 520, 217.	0.1	2
16	The 3d Parameters Of A (Nano)Crystal From Lattice Images At Two Tilts. <i>Microscopy and Microanalysis</i> , 1999, 5, 188-189.	0.4	2
17	Foreword: Special Section on "The Reliability of Advanced Microelectronic Packaging" Part I: Management of Thermal Effects. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020, 10, 1425-1426.	2.5	2
18	Oxide Reduction in Advanced Metal Stacks for Microelectronic Applications. <i>Materials Research Society Symposia Proceedings</i> , 2003, 786, 6331.	0.1	0

#	ARTICLE	IF	CITATIONS
19	Application of FIB/SEM and TEM to Bit Failure Analyses in SRAM Arrays. Materials Research Society Symposia Proceedings, 2003, 782, 1.	0.1	0
20	Surface Oxide Evolution on Al-Si Bond Wires. Materials Research Society Symposia Proceedings, 2003, 783, 7111.	0.1	0
21	High Contact-Resistance from Oxygen in Embedding ILD: An Investigation by TEM PEELS. Microscopy and Microanalysis, 2007, 13, .	0.4	0
22	Foreword: Special Section on “The Reliability of Advanced Microelectronic Packaging” Part II: Structure-Property Relationships. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1587-1588.	2.5	0
23	Via resistance increase accelerated by thermal stress. Microelectronics Reliability, 2021, 120, 114102.	1.7	0